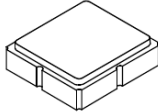


SF2621E-1

265.55 MHz
SAW Filter



SM3030-6

Maximum Ratings:

1. Input Power Level: 10 dBm
2. DC Voltage : 7.5V
3. Operating Temperature: -30°C to +85°C (1)
4. Storage Temperature: -40°C to +85°C
5. Moisture Sensitivity Level: 1
6. AEC-Q200 Qualified

Electrical Characteristics:

Terminating source impedance : $Z_s = 50 \Omega$

Terminating load impedance : $Z_L = 50 \Omega$

Item	Unit	Min.	Typ.(2)	Max.
Center frequency F_o	MHz	-	265.55	-
3dB Bandwidth	kHz	260	550	-
Insertion loss $F_o \pm 100\text{kHz}$	dB	-	3.2	4.0
Ripple $F_o \pm 100\text{kHz}$	dB		0.8	1.2
Group Delay Time Ripple $F_o \pm 100\text{kHz}$	usec		0.5	1.2
Attenuation (reference from 0dB)				
$F_o \pm 600\text{kHz}$	dB	25	30	-
$F_o \pm 1.2\text{MHz}$	dB	40	60	-
$F_o \pm 21.5\text{MHz} \sim F_o \pm 21.7\text{MHz}$	dB	60	63	-
Source impedance Z_s	Ω	-	50	-
Load impedance Z_L	Ω	-	50	-

Notes:

- (1). In production, devices will be tested at room temperature to a guardbanded specification to ensure electrical compliance over temperature.
- (2). Typical values are based on average measurements at room temperature.



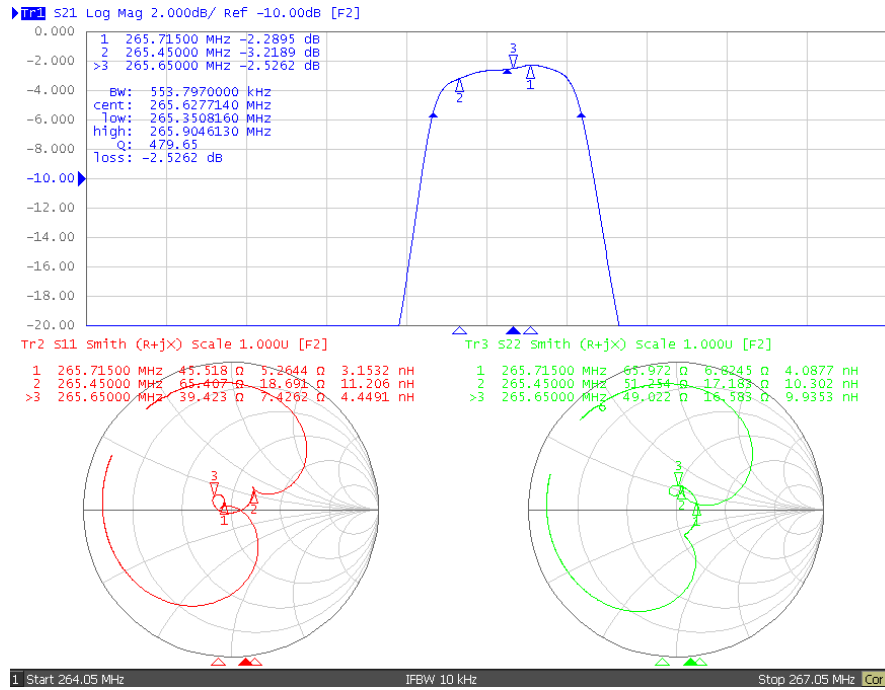
CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

NOTES:

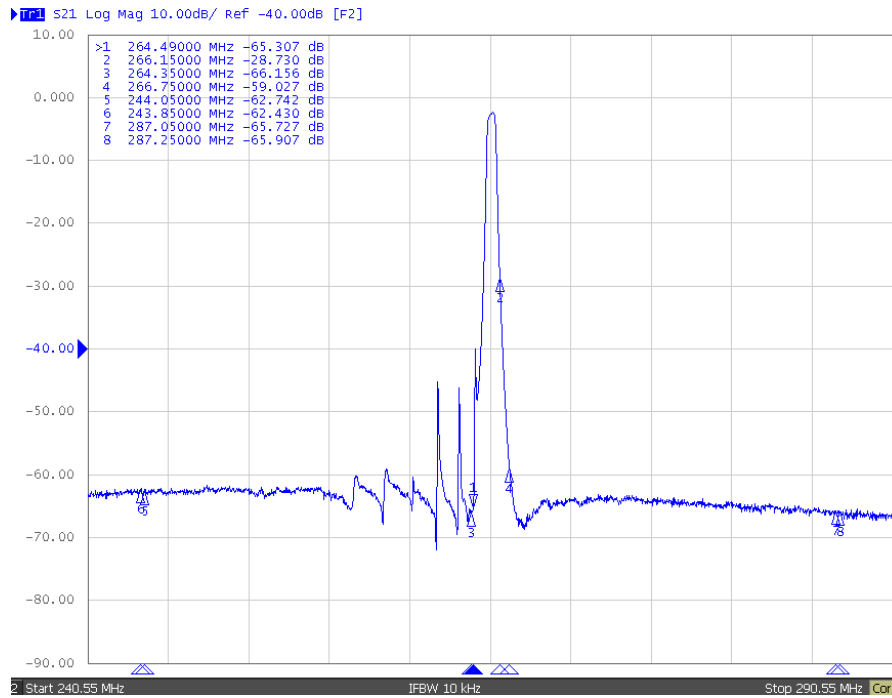
1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. RoHS compliant from the first date of manufacture.

Transfer function:

(1) S21 response (span : 3 MHz)

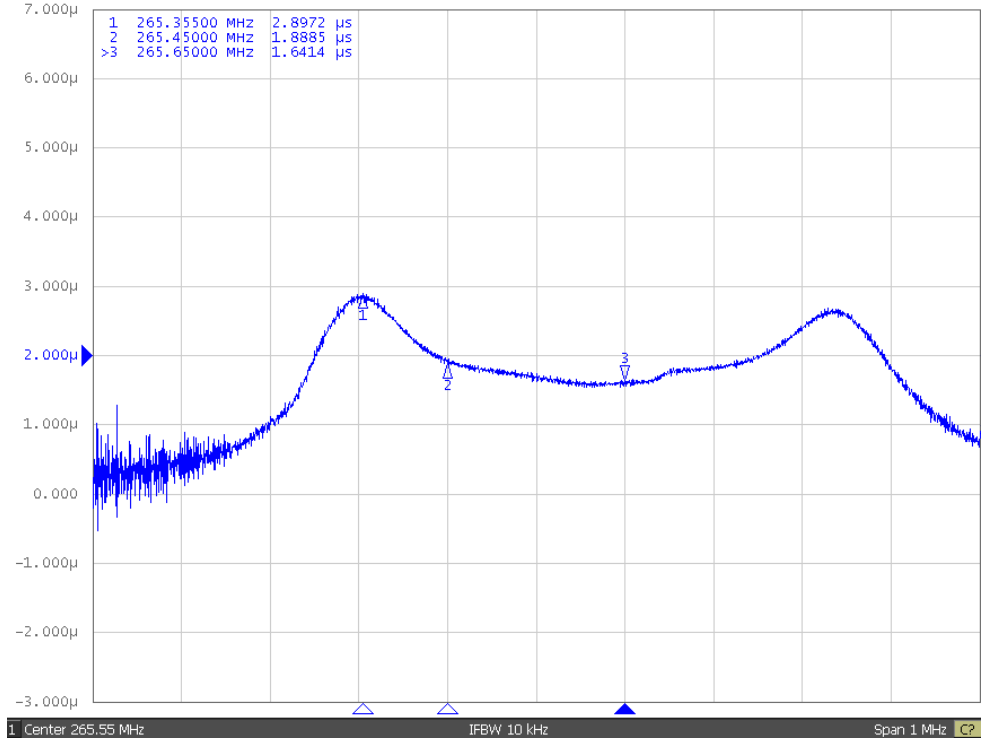


(2) S21 response for wide

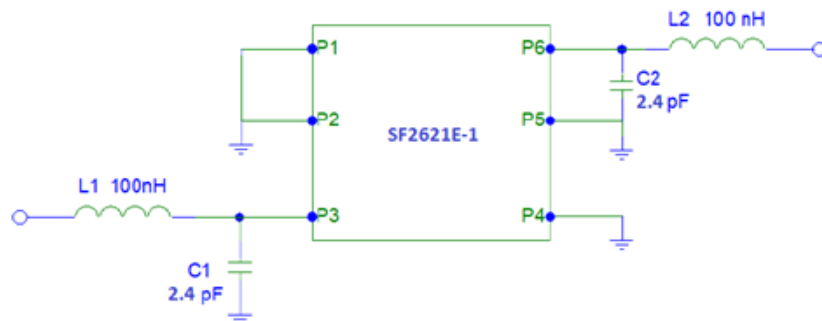


(3) Group delay

S21 Delay 1.000µs/ Ref 2.000µs [F2]

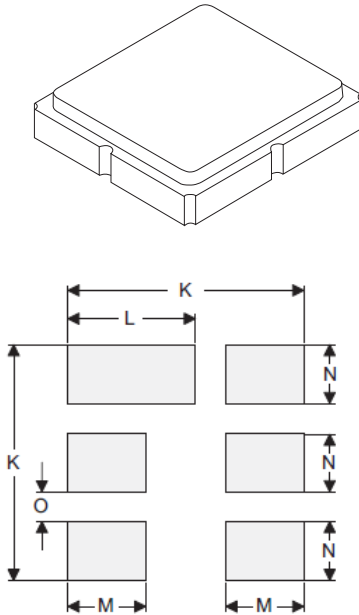


A YUgi fYa Ybh7 jfW]h (at 25 °C)



SM3030-6 Case

6-Terminal Ceramic Surface-Mount Case 3.0 X 3.0 mm Nominal Footprint



PCB Footprint Top View

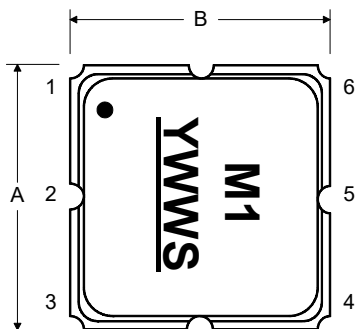
Case and PCB Footprint Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.87	3.00	3.13	0.113	0.118	0.123
B	2.87	3.00	3.13	0.113	0.118	0.123
C	1.12	1.25	1.38	0.044	0.049	0.054
D	0.77	0.90	1.03	0.030	0.035	0.040
E	2.67	2.80	2.93	0.105	0.110	0.115
F	1.47	1.60	1.73	0.058	0.063	0.068
G	0.72	0.85	0.98	0.028	0.033	0.038
H	1.37	1.50	1.63	0.054	0.059	0.064
I	0.47	0.60	0.73	0.019	0.024	0.029
J	1.17	1.30	1.43	0.046	0.051	0.056
K		3.20			0.126	
L		1.70			0.067	
M		1.05			0.041	
N		0.81			0.032	
O		0.38			0.015	

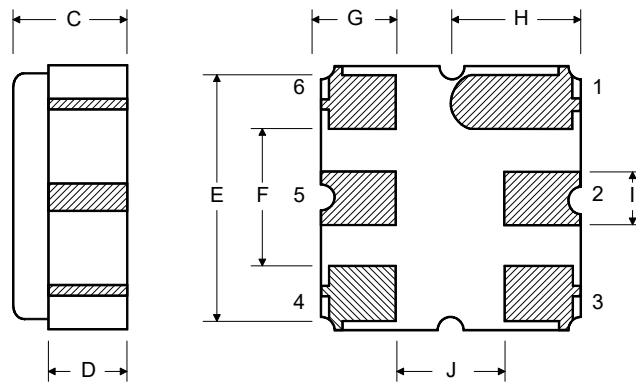
Case Materials

Materials	
Solder Pad Plating	0.3 to 1.0 μm Gold over 1.27 to 8.89 μm Nickel
Lid Plating	2.0 to 3.0 μm Nickel
Body	Al_2O_3 Ceramic

TOP VIEW



BOTTOM VIEW



PACKING:

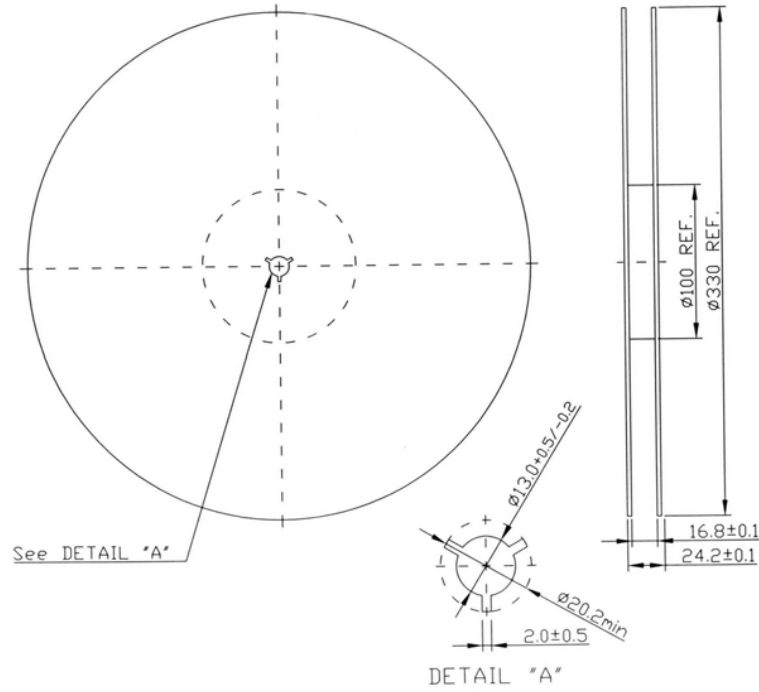
REEL DIMENSION

Tape and Reel Standard per ANSI/EIA-481

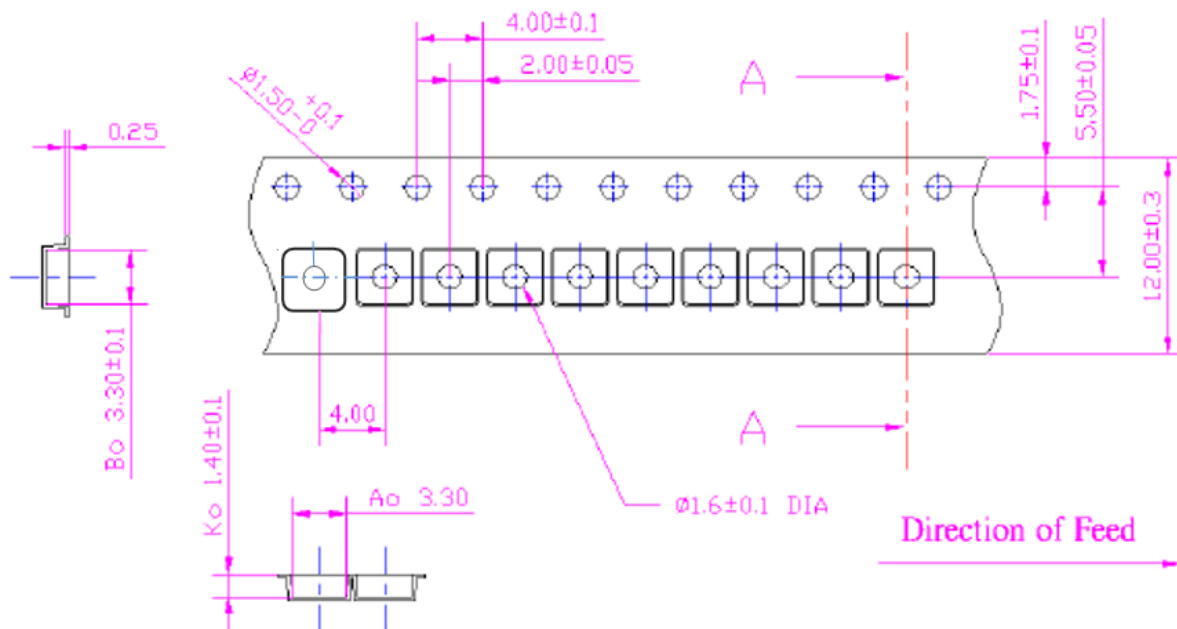
Reel Count:

7" = 500

13" = 3000



Tape Dimensions:



Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C +0/-5°C peak (10 seconds).
4. Time: 5 times maximum.

